

ABSTRACT

A photosensitive resin composition for a laser engravable printing substrate, comprising resin (a) having a polymerizable unsaturated group whose number average molecular weight is in the range of 1000 to 20×10^4 , organic compound (b) having a polymerizable unsaturated group whose number average molecular weight is <1000 and organosilicon compound (c) having at least one Si-O bond in each molecule and having no polymerizable unsaturated group in molecules, wherein the content of organosilicon compound (c) is in the range of 0.1 to 10 wt.% based on the whole of photosensitive resin composition.